

## TITLE

### DETECTABLE FLAT PANEL DISPLAY AND RECOGNITION SYSTEM THEREFOR

#### BACKGROUND OF THE INVENTION

##### 5      1. Field of the Invention:

The present invention relates to a flat panel display, and more particularly to a flat panel display including a detectable metal pattern and a recognition system therefor.

##### 10     2. Description of the Related Art:

Presently, flat panel displays are important electronic products, used in personal computers, notebook computers, televisions, and mobile phones. Organic light-emitting diodes (OLED) are LEDs with an organic layer acting as the active layer, increasingly applied in flat panel displays due to advantages, such as low voltage operating, high brightness, light weight, slim profile, wide viewing angle, and highly effective contrast ratio.

15      OLEDs are classified as active matrix and passive matrix types according to driving methods. Active matrix organic light-emitting diodes (AMOLED) are generally driven by a thin film transistor (TFT).

20      Conventional OLEDs only provide display function, without detectable elements for recognition equipment.

##### 25                      SUMMARY OF THE INVENTION

An object of the present invention is to solve the above-mentioned problem and provide a detectable flat panel display.

To achieve the above objects, according to a first embodiment of the present invention, the detectable flat panel display includes: a substrate including a circuit region and a display region; a circuit device disposed in the circuit region of the substrate; a display device disposed in the display region of the substrate; and a metal pattern formed in the circuit region, capable of reflecting light such that the reflected light is detectable by recognition equipment. The metal pattern can be a source electrode, a drain electrode, or a gate.

According to a second embodiment of the present invention, the detectable flat panel display includes: a substrate including a circuit region and a display region; a circuit device disposed in the circuit region of the substrate; a display device disposed in the display region of the substrate; and a metal pattern formed in the display region, capable of reflecting light such that the reflected light is detectable by recognition equipment.

According to a third embodiment of the present invention, the detectable organic light-emitting diode display includes: a substrate including a thin film transistor (TFT) region and an organic light-emitting diode (OLED) region; a thin film transistor disposed in the TFT region of the substrate, having a first metal pattern capable of reflecting light such that the reflected light is detectable by recognition equipment; a planarizing insulating layer covering the thin film transistor, having a contact window to expose the first metal pattern; a transparent anode disposed in the OLED region of the substrate, electrically connected to the

first metal pattern; a transparent insulating cover layer covering a portion of the anode in a contact window position; an organic light-emitting layer disposed on the anode and the insulating cover layer; and a transparent  
5 cathode disposed on the organic light-emitting layer.

According to a fourth embodiment of the present invention, the detectable organic light-emitting diode display includes: a substrate including a thin film transistor (TFT) region and an organic light-emitting  
10 diode (OLED) region; a thin film transistor disposed in the TFT region of the substrate; an anode disposed in the OLED region of the substrate; an organic light-emitting diode disposed on the anode; and a transparent cathode disposed on the organic light-emitting layer. One or both  
15 of the organic light-emitting layer and the transparent cathode has an opening, with a second metal pattern disposed therein, capable of reflecting light such that the reflected light is detectable by recognition equipment.

20 The present invention also provides a recognition system including a detectable flat panel display and recognition equipment. The detectable flat panel display includes: a substrate including a circuit region and a display region; a circuit device disposed in the circuit  
25 region of the substrate; and a display device disposed in the display region of the substrate.

The detectable flat panel display meets at least one of the following requirements:

a first metal pattern is disposed in the circuit  
30 region, wherein any layer above the first metal pattern

is transparent or the first metal pattern is the outermost layer, such that the first metal pattern is detectable by the recognition equipment; or

5 a second metal pattern is disposed in the display region, wherein any layer above the second metal pattern is transparent or the second metal pattern is the outermost layer, such that the second metal pattern is detectable by the recognition equipment.

10 The recognition equipment, such as a light pen, of the present invention can include a light source, a receiver, and a signal feedback device. When the light emitted from the light source irradiates the flat panel display, the light is reflected by the first and/or second metal pattern. The receiver receives a signal of the  
15 reflected light and transmits the signal to the signal feedback device. The signal feedback device transmits the signal back to the flat panel display.

#### BRIEF DESCRIPTION OF THE DRAWINGS

20 The present invention will become more fully understood from the detailed description given hereinbelow and the accompanying drawings, given by way of illustration only and thus not intended to be limitative of the present invention.

25 FIG. 1 is a top view of a pixel of an organic light-emitting diode display according to a first embodiment of the present invention.

FIGS. 2a to 2c are cross-sections taken along line 2-2 of FIG. 1, illustrating the process flow of

fabricating an organic light-emitting diode display according to a first embodiment of the present invention.

FIG. 3 shows a schematic diagram of a recognition system of the present invention.

5        FIG. 4 is a top view of a pixel of an organic light-emitting diode display according to a second embodiment of the present invention.

FIG. 5a is a cross-section taken along line 5a-5a of FIG. 4.

10       FIGS. 5b and 5c show different arrangements of the second metal pattern.

FIG. 6 is top view showing a plurality of pixels of an organic light-emitting diode display of the present invention.

15                    **DETAILED DESCRIPTION OF THE INVENTION**

The flat panel display of the present invention includes a circuit device and a display device, at least one of which includes a detectable metal pattern. That is, any layer over the metal pattern is transparent or the  
20       metal pattern constitutes the outermost layer, such that the metal pattern is detectable by recognition equipment.

FIG. 1 is a top view of a pixel of an organic light-emitting diode display according to a first preferred embodiment of the present invention, and FIG.  
25       2c is a cross-section taken along line 2-2. In this embodiment, the circuit device is a thin film transistor (TFT) and the display device is an organic light-emitting diode (OLED), as an example, but the invention is not limited thereto.

Referring to FIG. 1, the pixel includes a data line (DL) extending along a Y axis, a scanning line (SL) extending along an X axis, a circuit region I, and a display region II. Referring to FIG. 2c, a substrate 10 includes the circuit region I and the display region II. A circuit device 20 is disposed in the circuit region I of the substrate 10, and a display device 50 is disposed in the display region II of the substrate. For ease of explanation, the circuit device 20 is a TFT and the display device 50 is an OLED, as an example.

The process flow of fabricating the OLED display of the first embodiment is shown in FIG. 1 and FIGS. 2a to 2c. First, referring to FIGS. 1 and 2a, a metal layer M1 (not shown) is formed on the substrate 10 over the entire surface. The metal layer M1 is then patterned by photolithography and etching to form the scanning line (SL) and a gate (G). Next, a gate insulating layer 21, an active layer 22, and a doped layer (not shown) are formed sequentially. Next, the doped layer is defined by photolithography and etching to form a source region 23a and a drain region 23b.

The gate insulating layer 21 can be a single layer of silicon oxide, silicon nitride, or silicon oxynitride (SiON), or a multi-layered structure of a combination thereof. The active layer 22 can be an amorphous silicon layer formed by plasma-enhanced chemical vapor deposition (PECVD) or low pressure chemical vapor deposition (LPCVD) using silane ( $\text{SiH}_4$ ) as the reacting gas. The active layer 22 can also be a polysilicon layer formed by first forming an amorphous silicon layer and then performing excimer

laser annealing (ELA) at a low temperature. The doped layer can be a doped amorphous silicon layer and can be an n<sup>+</sup>-type doped layer formed by CVD using silane and PH<sub>3</sub> as the reacting gases. The n<sup>+</sup>-type doped layer provides carriers. Next, the n<sup>+</sup>-type doped layer is defined by photolithography and etching to form an n<sup>+</sup>-type source region 23a and an n<sup>+</sup>-type drain region 23b.

Subsequently, a metal layer M2 (not shown) is formed on the substrate 10 over the entire surface. The metal layer M2 is then defined by photolithography and etching to form the data line (DL), a source electrode S on the source region 23a, and a drain electrode D on the drain region 23b. Thus, a thin film transistor 20 in the circuit region I is complete.

Subsequently, referring to FIG. 2b, a planarizing insulating layer 32 is formed on the above structure to cover the thin film transistor 20. The planarizing insulating layer 32 can be a photoresist material or a dielectric material and can be formed by spin coating. Since the planarizing insulating layer 32 is formed by spin coating, it is thick and provides a flat surface. Thus, subsequently formed film on the planarizing insulating layer 32 is flatter.

Subsequently, a via hole 34 is formed in the planarizing insulating layer 32 to expose the drain electrode D. Next, a transparent anode 51, such as indium tin oxide (ITO), is formed on the planarizing insulating layer 32. The transparent anode 51 simultaneously fills in the via hole 34 to electrically connect to the drain electrode D.

Subsequently, referring to FIG. 2c, a transparent insulating cover layer 36 is formed to cover the transparent anode 51 at the via hole 34 position. Next, an organic light-emitting layer 52 is formed on the anode 51 and the insulating cover layer 36. Next, a cathode 53, such as indium zinc oxide (IZO), is formed on the organic light-emitting layer 52. Thus, an organic light-emitting diode 50 in the display region II of the substrate 10 is complete, and includes the transparent anode 51, the organic light-emitting layer 52, and the transparent cathode 53.

In the first embodiment of the present invention, all layers above the drain electrode D, including the transparent anode 51, the transparent insulating cover layer 36, the organic light-emitting layer 52, and the transparent cathode 53, are transparent. Thus, the drain electrode D is exposed to the display surface. The exposed drain electrode is referred to as a first metal pattern and labeled P1 (as shown in FIG. 1). The exposed first metal pattern P1 is detectable by recognition equipment.

FIG. 3 is a schematic diagram of a recognition system of the present invention. The recognition system includes a detectable flat panel display 100 and recognition equipment 200. The detectable flat panel display 100 can be the organic light-emitting diode display of the first embodiment. A first metal pattern P1 is disposed in the circuit region I of the detectable flat panel display 100, with all layers above the first metal pattern P1 transparent. The recognition equipment 200 can be a light

pen and can include a light source 210, a receiver 220, and a signal feedback device 230.

5 The operating principle of the recognition system of the present invention is shown in FIG. 3. When light 1 from the light source 210 irradiates the flat panel display 100, it can be reflected by the exposed first metal pattern (P1). The receiver 220 receives the signal of the reflected light 2 and transmits the signal to the signal feedback device 230. The signal feedback device 230  
10 transmits the signal back to the flat panel display 100. In this way, the position of the light pen on a monitor is detected.

FIG. 4 is a top view of a pixel of an organic light-emitting diode display according to a second  
15 embodiment of the present invention, and FIG. 5a is a cross-section taken along line 5a-5a. In this embodiment, the circuit device is a thin film transistor (TFT) and the display device an organic light-emitting diode (OLED), as an example, but the invention is not limited thereto.

20 Referring to FIG. 4, the pixel includes a data line (DL) extending along a Y axis, a scanning line (SL) extending along an X axis, a circuit region I, and a display region II. For ease of explanation, FIG. 5a only shows the display region II. Any suitable circuit device  
25 other than a TFT can be disposed in the circuit region I. Referring to FIG. 5a, a display device 60 is formed in the display region II of the substrate 10. For ease of explanation, the display device 60 is an OLED as an example, but the invention is not limited thereto.

The process flow of fabricating the OLED display of the second embodiment is shown in FIGS. 4 and 5a. First, a circuit device is formed in the circuit region I of the substrate 10. For example, a thin film transistor 20 can be formed in the circuit region I according to the method of FIG. 2a, but the invention is not limited to thereto. Specifically speaking, a metal layer M1 (not shown) is formed on the substrate 10 over the entire surface. The metal layer M1 is then patterned by photolithography and etching to form the scanning line (SL) and a gate (G). Next, a gate insulating layer 21, an active layer 22, and a doped layer (not shown) are formed sequentially. Next, the doped layer is defined by photolithography and etching to form a source region 23a and a drain region 23b.

Subsequently, a metal layer M2 (not shown) is formed on the substrate 10 over the entire surface. The metal layer M2 is then defined by photolithography and etching to form the data line (DL), a source electrode S on the source region 23a, and a drain electrode D on the drain region 23b. Thus, a thin film transistor 20 in the circuit region I is complete.

Subsequently, referring to FIG. 5a, an anode 61 and an organic light-emitting layer 62 are then sequentially formed on the above structure. Next, an opening 621 is formed in the organic light-emitting layer 62 and a second metal pattern P2 is filled in the opening 621. Next, a transparent anode 63 is formed on the light-emitting layer 62 and the second metal pattern P2. Thus, an organic light-emitting diode 60 in the display region II of the substrate 10 is complete, and includes the anode 61, the

organic light-emitting layer 62, the second metal pattern P2, and the transparent cathode 63.

Refer to FIG. 3, which shows a schematic diagram of a recognition system of the present invention. The recognition system includes a detectable flat panel display 100 and recognition equipment 200. The detectable flat panel display 100 can be the organic light-emitting diode display shown in FIG. 5a. The recognition equipment 200 can be a light pen which includes a light source 210, a receiver 220, and a signal feedback device 230.

In FIG. 5a of the second embodiment of the present invention, the film on the second metal pattern P2 is the transparent cathode 63. Such that the second metal pattern P2 is exposed to the display surface. The exposed second metal pattern P2 is detectable by recognition equipment 200.

The operating principle is the same as that described in the first embodiment. That is, when light 1 from the light source 210 irradiates the flat panel display 100, it can be reflected by the exposed second metal pattern (P2). The receiver 220 receives the signal of the reflected light 2 and transmits the signal to the signal feedback device 230. The signal feedback device 230 transmits the signal back to the flat panel display 100. In this way, the position of the light pen on a monitor is detected.

FIG. 5a shows that although the second metal pattern P2 is not the outermost layer, any layer above the second metal pattern P2 is transparent. Thus, the second metal

pattern P2 in FIG. 5a is exposed to the display surface and is detectable by recognition equipment 200.

FIG. 5b shows a different arrangement of the second metal pattern P2 of the second embodiment of the present invention, in which the second metal pattern P2 is the outermost layer. Referring to FIG. 5b, after the circuit device is formed in the circuit region I of the substrate 10, an anode 71, an organic light-emitting layer 72, and a cathode 73 are sequentially formed in the display region II of the substrate 10. Next, an opening 731 is formed in the cathode 73 and a second metal pattern P2 is filled in the opening 731. Thus, an organic light-emitting diode 70 in the display region II of the substrate 10 is complete, and includes the anode 71, the organic light-emitting layer 72, the cathode 73, and the second metal pattern P2.

Refer to FIG. 3, which shows a schematic diagram of a recognition system of the present invention. The recognition system includes a detectable flat panel display 100 and recognition equipment 200. The detectable flat panel display 100 can be the organic light-emitting diode display shown in FIG. 5b. The recognition equipment 200 can be a light pen which includes a light source 210, a receiver 220, and a signal feedback device 230.

In FIG. 5b, the second metal pattern P2 is the outermost layer and exposed to the display surface. Therefore, according to the same principle as mentioned, the exposed second metal pattern P2 can be detectable by the recognition equipment 200 (such as a light pen) as can the position of the light pen on a monitor.

FIG. 5c shows another arrangement of the second metal pattern P2 of the second embodiment of the present invention. Referring to FIG. 5c, after the circuit device is formed in the circuit region I of the substrate 10, an anode 81, an organic light-emitting layer 82, and a cathode 83 are sequentially formed in the display region II of the substrate 10. Next, an opening 831 is formed in the organic light-emitting layer 82 and the cathode 83 and a second metal pattern P2 is filled in the opening 831. Thus, an organic light-emitting diode 80 in the display region II of the substrate 10 is complete, and includes the anode 81, the organic light-emitting layer 82, the cathode 83, and the second metal pattern P2.

Refer to FIG. 3, which shows a schematic diagram of a recognition system of the present invention. The recognition system includes a detectable flat panel display 100 and recognition equipment 200. The detectable flat panel display 100 can be the organic light-emitting diode display shown in FIG. 5c. The recognition equipment 200 can be a light pen which includes a light source 210, a receiver 220, and a signal feedback device 230.

In FIG. 5c, the second metal pattern P2 is the outermost layer and exposed to the display surface. Therefore, according to the same principle mentioned above, the exposed second metal pattern P2 can be detectable by the recognition equipment 200 (such as a light pen) as can the position of the light pen on a monitor.

FIG. 6 is a top view of a plurality of pixels of an organic light-emitting diode display of the present

invention. As shown in the figure, a metal pattern P is disposed in the circuit device or the display device in each pixel (R, G, or B pixel) according to requirements. Any layers above the metal pattern P are transparent or  
5 the metal pattern P is the outmost layer. Thus, according to the principle described above, the exposed metal pattern P can be detectable by recognition equipment (such as a light pen) as can the light pen position on a monitor. The detectable metal patterns P in various pixels can have  
10 different positions and arrangement.

In conclusion, a metal pattern is disposed in the circuit or display device of the OLED device of the present invention. Layers above the metal pattern are transparent or the metal pattern is the outmost layer, such that the  
15 metal layer is detectable by recognition equipment (such as a light pen). When light from the light source of the light pen irradiates the flat panel display, it can be reflected by the exposed metal pattern. The receiver receives the signal of the reflected light and transmits  
20 the signal to the signal feedback device. The signal feedback device transmits the signal back to the flat panel display. In this way, the position of the light pen on a monitor is detected.

The foregoing description of the preferred  
25 embodiments of this invention has been presented for purposes of illustration and description. Obvious modifications or variations are possible in light of the above teaching. The embodiments chosen and described provide an excellent illustration of the principles of  
30 this invention and its practical application to thereby

enable those skilled in the art to utilize the invention  
in various embodiments and with various modifications as  
are suited to the particular use contemplated. All such  
modifications and variations are within the scope of the  
5 present invention as determined by the appended claims  
when interpreted in accordance with the breadth to which  
they are fairly, legally, and equitably entitled.